

# D1FL20U

**PRV : 200 Volts**  
**Io : 1.1 Ampere**

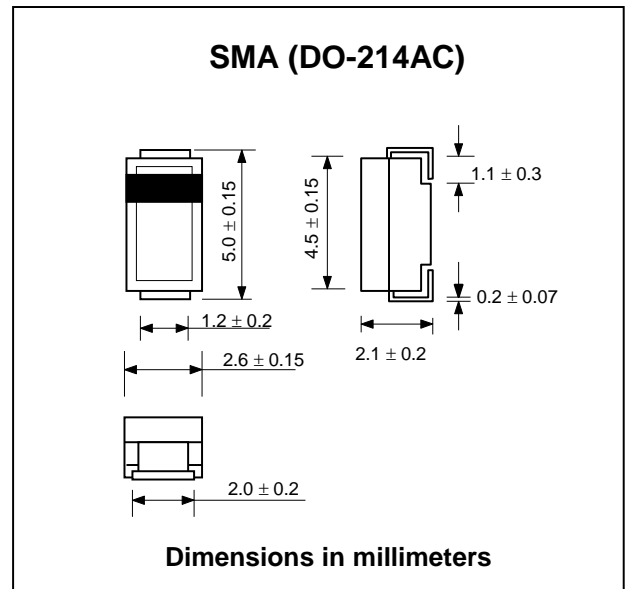
### FEATURES :

- \* Glass passivated junction chip
- \* High current capability
- \* High surge current capability
- \* High reliability
- \* Low reverse current
- \* Low forward voltage drop
- \* Super fast recovery time
- \* **Pb / RoHS Free**

### MECHANICAL DATA :

- \* Case : SMA Molded plastic
- \* Epoxy : UL94V-0 rate flame retardant
- \* Lead : Lead Formed for Surface Mount
- \* Polarity : Color band denotes cathode end
- \* Mounting position : Any
- \* Weight : 0.067 gram

## SURFACE MOUNT SUPER FAST RECTIFIERS



### MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS (If not specified Tl=25 °C)

RATING	SYMBOL	VALUE	UNIT
Maximum Recurrent Peak Reverse Voltage	VRRM	200	V
Maximum RMS Voltage	VRMS	140	V
Maximum DC Blocking Voltage	VDC	200	V
Maximum Average Forward Current ( 50 Hz sine wave, R - load , T <sub>a</sub> = 25 °C )	I <sub>o</sub>	1.1 (on aluminum substrate) 0.84 (on glass-epoxy substrate)	A
Maximum Peak Forward Surge Current ( 50 Hz sine wave, Non - repetitive 1 cycle peak value, T <sub>j</sub> =25 °C )	IFSM	20	A
Maximum Peak Forward Voltage at I <sub>F</sub> = 1.1 A	V <sub>F</sub>	0.98	V
Maximum DC Reverse Current at Rated DC Blocking Voltage	I <sub>R</sub>	10	μA
Maximum Reverse Recovery Time ( Note 1 )	T <sub>rr</sub>	35	ns
Maximum Thermal Resistance Junction to Lead	R <sub>θJL</sub>	23	°C/W
Maximum Thermal Resistance Junction to Ambient	R <sub>θJA</sub>	108 (on aluminum substrate) 157 (on glass-epoxy substrate)	°C/W
Storage Temperature Range	T <sub>STG</sub>	- 55 to + 150	°C

### Notes :

( 1 ) Reverse Recovery Test Conditions : I<sub>F</sub> = 0.5 A, I<sub>R</sub> = 1.0 A, I<sub>rr</sub> = 0.25 A.

RATING AND CHARACTERISTIC CURVES ( D1FL20U )

FIG.1 - DERATING CURVE

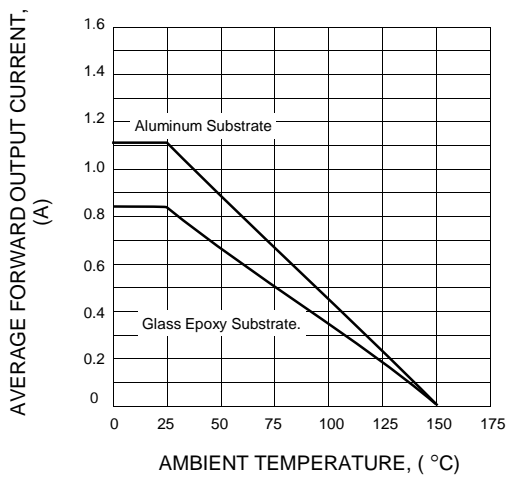


FIG.2 - PEAK SURGE FORWARD CAPABILITY

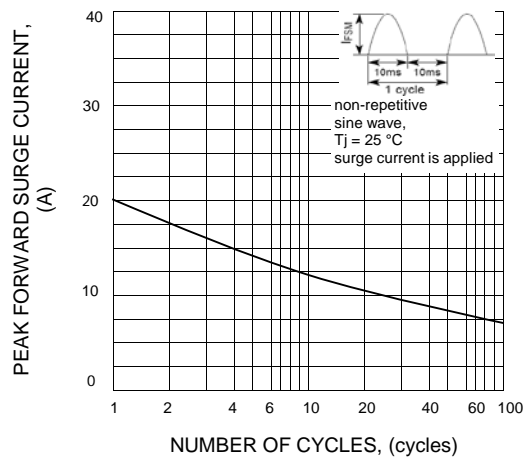


FIG.3 - FORWARD CHARACTERISTICS

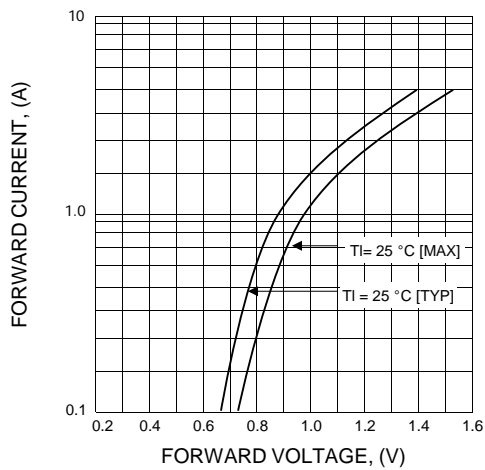


FIG.4 - JUNCTION CAPACITANCE

